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#3 Pre Amdt. A
5-2-03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Downes, Jr. *et al.*

Art Unit:

Serial No.:

Dkt. No.: EN9-97-075US3

Filed:

Examiner:

Title: **ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT LAYER**

Commissioner for Patents
Washington, DC 20231

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination

In the Specification:

Page 1, between lines 1 and 2, insert: - [This application is a divisional of Serial No.

09/540,172, filed on March 31, 2000, which was a continuation-in-part of Serial No. 09/346,356,
filed on July 2, 1999.--

In the Claims:

Please cancel claims 1-13 and 36-38. The following claims 14-35 are currently pending.

New Claims 36-38 have been added.

14. A method of making a multi-layered interconnect structure, comprising the steps of:

providing a thermally conductive layer including first and second opposing surfaces;